

N-Channel Enhancement Mode Power MOSFET

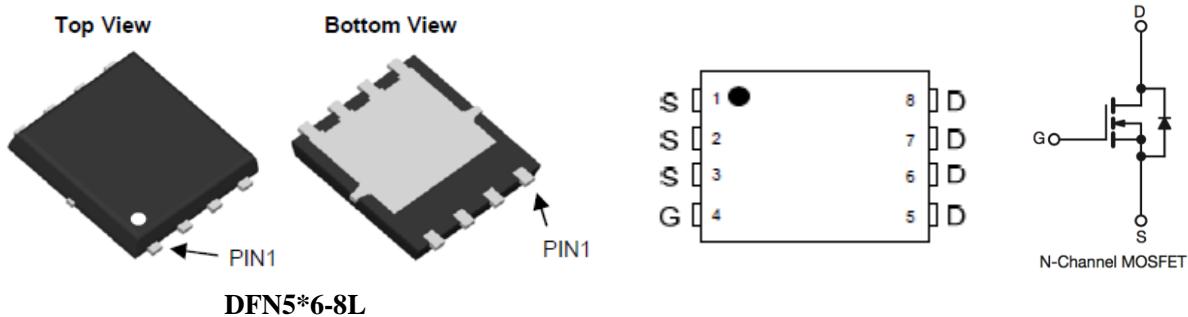
● Features

$V_{DS} = 30V$,
 $I_D = 49A$
 $R_{DS(ON)} @ V_{GS} = 10V$, Max $7m\Omega$
 $R_{DS(ON)} @ V_{GS} = 4.5V$, Max $10.8m\Omega$

● General Description

- DC/DC conversion
- Battery protection
- Load switching
- DC/AC inverters

● Pin Configurations



● Absolute Maximum Ratings @ $T_A=25^\circ C$ unless otherwise noted

Parameter		Symbol	Ratings	Unit
Drain-Source Voltage		V_{DSS}	30	V
Gate-Source Voltage		V_{GSS}	± 20	V
Drain Current (Continuous) *AC	$T_c=25^\circ C$	I_D	46.5	A
	$T_c=70^\circ C$		37.2	
Drain Current (Pulse) *B		I_{DM}	100	A
Power Dissipation	$T_c=25^\circ C$	P_D	25	W
Operating Temperature/ Storage Temperature		T_J/T_{STG}	-55~150	°C

● Thermal Resistance Ratings

Parameter	Symbol	Typical	Maximum	Unit
Maximum Junction-to-Ambient	R_{thJA}	30	37	°C/W
Maximum Junction-to-Case (Drain)	R_{thJC}	4	5	

● Electrical Characteristics @ $T_A=25^\circ C$ unless otherwise noted

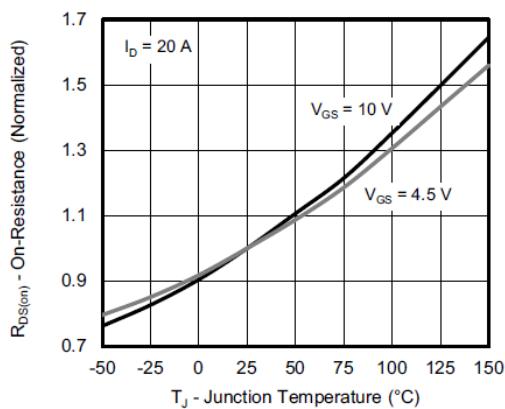
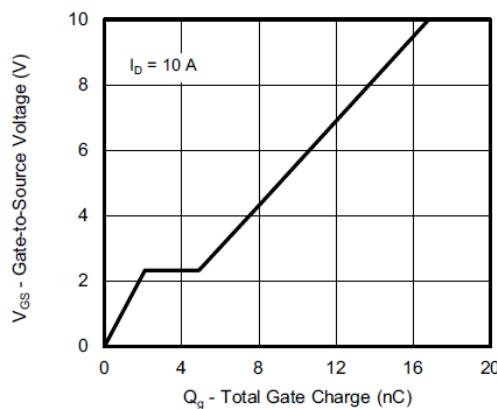
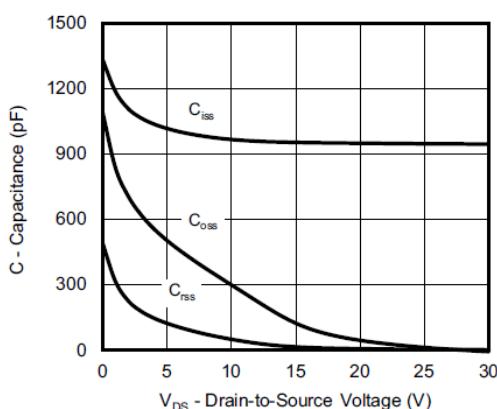
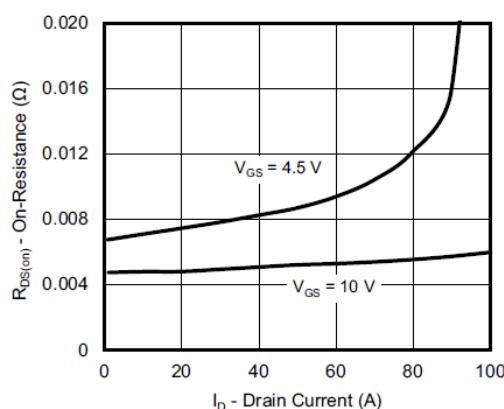
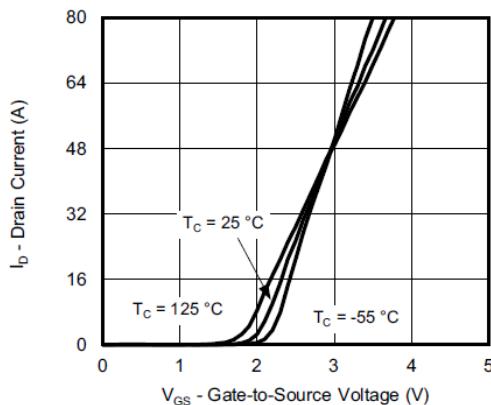
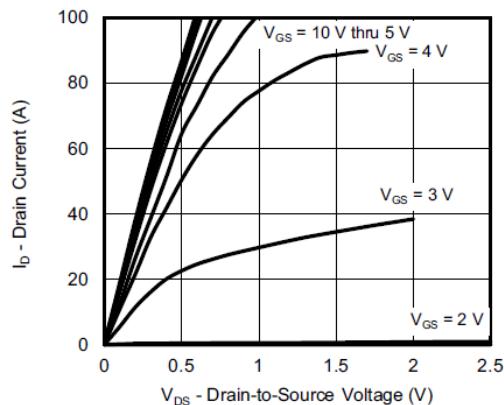
Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
Static						
Drain-Source Breakdown Voltage	$V_{(BR)DSS}$	$V_{GS} = 0V, I_D = 250\mu A$	30	--	--	V
Zero Gate Voltage Drain Current	I_{DSS}	$V_{DS} = 30 V, V_{GS} = 0V$	--	--	1	μA
Gate Threshold Voltage	$V_{GS(TH)}$	$V_{GS} = V_{DS}, I_{DS} = 250\mu A$	1	--	2.5	V
Gate Leakage Current	I_{GSS}	$V_{GS} = \pm 20V, V_{DS} = 0V$	--	--	± 100	nA
Drain-Source On-state Resistance	$R_{DS(on)}$	$V_{GS} = 10V, I_D = 20A$	--	--	7	$m\Omega$
	$R_{DS(on)}$	$V_{GS} = 4.5V, I_D = 20A$	--	--	10.8	$m\Omega$
Diode Forward Voltage	V_{SD}	$I_{SD} = 1A, V_{GS} = 0V$	--	--	1.2	V
Diode Forward Current *AC	I_S	$T_C = 25^\circ C$	--	--	35	A
Switching						
Total Gate Charge	Q_g	$V_{GS} = 10V, V_{DS} = 15V, I_D = 10A$	--	16.8	--	nC
Gate-Source Charge	Q_{gs}		--	2.1	--	nC
Gate-Drain Charge	Q_{gd}		--	2.8	--	nC
Turn-on Delay Time	$t_{d(on)}$	$V_{DD} = 15 V, R_L = 1.5\Omega$ $I_D \geq 10 A, V_{GEN} = 10 V, R_g = 1\Omega$	--	7	--	ns
Turn-on Rise Time	t_r		--	28	--	ns
Turn-off Delay Time	$t_{d(off)}$		--	14	--	ns
Turn-Off Fall Time	t_f		--	8	--	ns
Dynamic						
Input Capacitance	C_{iss}	$V_{DS} = 15V, V_{GS} = 0V, f = 1.0MHz$	--	947	--	pF
Output Capacitance	C_{oss}		--	157	--	pF
Reverse Transfer Capacitance	C_{rss}		--	10	--	pF

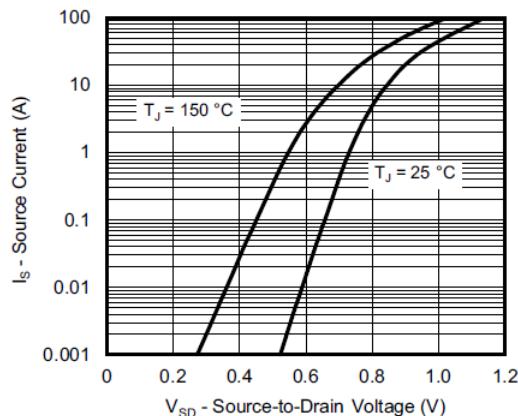
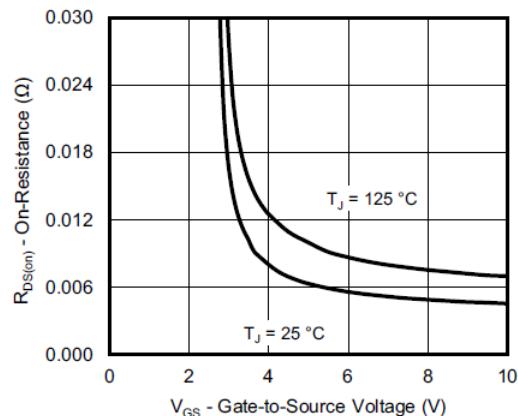
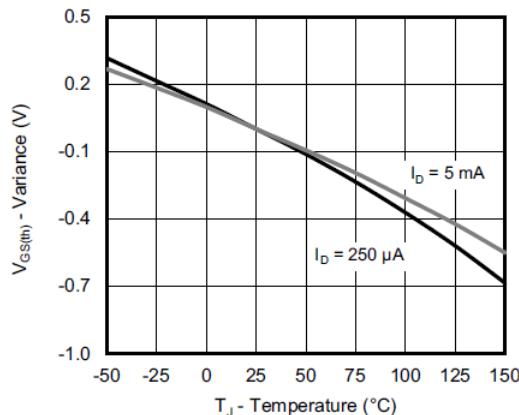
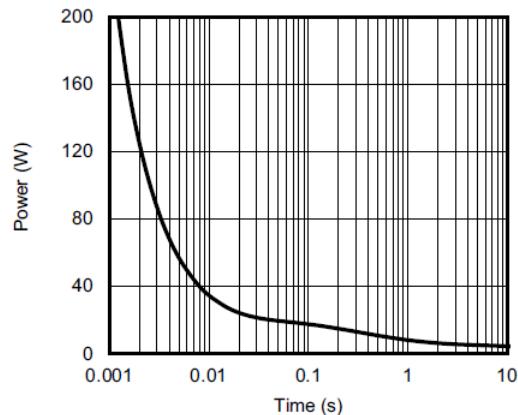
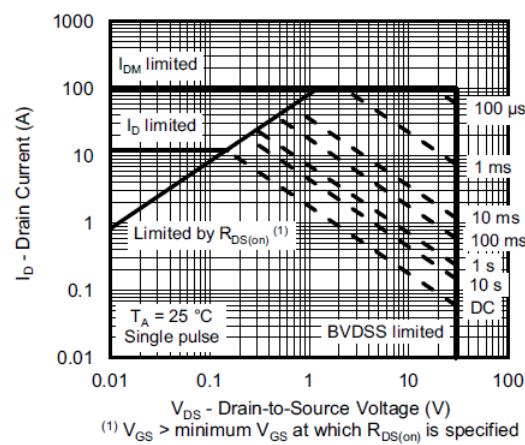
A: The value of $R_{\theta JA}$ is measured with the device mounted on 1in² FR-4 board with 2oz. Copper, in a still air environment with $T_A=25^\circ C$. The value in any given application depends on the user's specific board design.

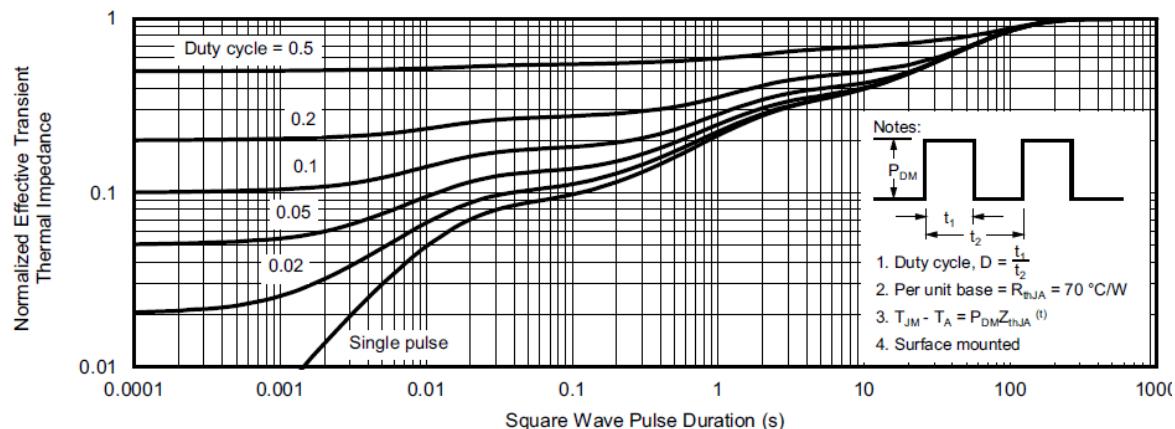
B: Repetitive rating, pulse width limited by junction temperature.

C: The current rating is based on the $t \leq 10s$ junction to ambient thermal resistance rating.

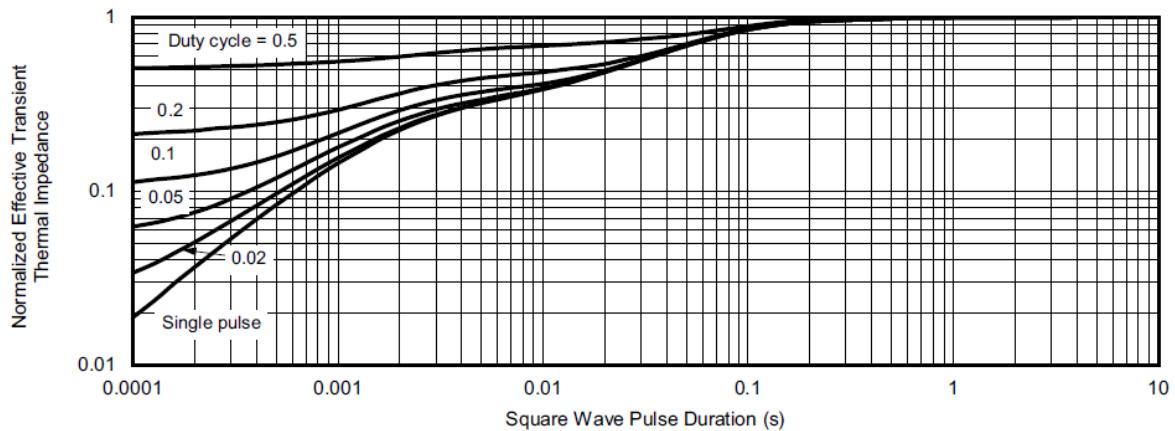
- Typical Performance Characteristics (($T_J = 25^\circ\text{C}$, unless otherwise noted))




Source-Drain Diode Forward Voltage

On-Resistance vs. Gate-to-Source Voltage

Threshold Voltage

Single Pulse Power, Junction-to-Ambient

Safe Operating Area

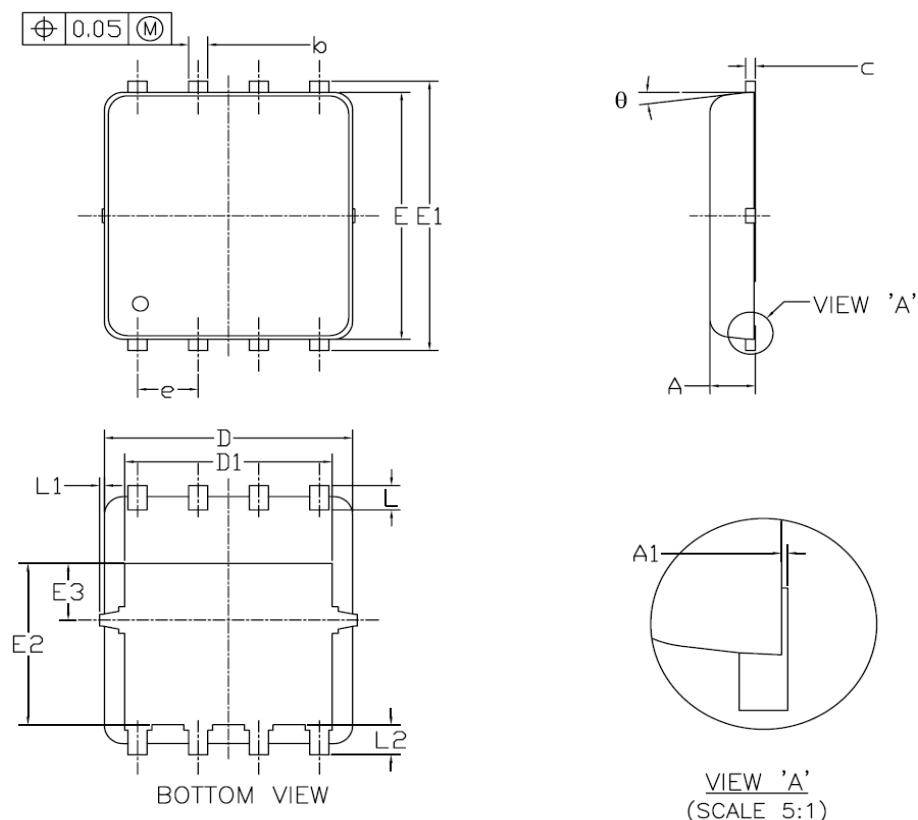
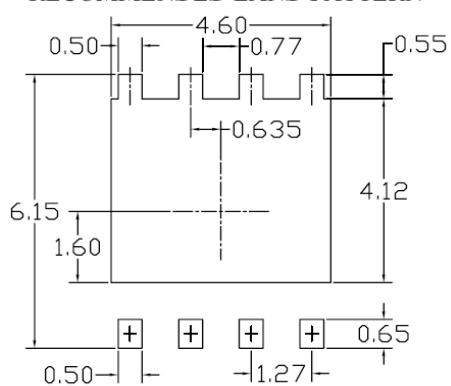


Normalized Thermal Transient Impedance, Junction-to-Ambient



Normalized Thermal Transient Impedance, Junction-to-Case

- Package Information


RECOMMENDED LAND PATTERN


SYMBOLS	DIMENSIONS IN MILLIMETERS			DIMENSIONS IN INCHES		
	MIN	NOM	MAX	MIN	NOM	MAX
A	0.85	0.95	1.00	0.033	0.037	0.039
A1	0.00	—	0.05	0.000	—	0.002
b	0.30	0.40	0.50	0.012	0.016	0.020
c	0.15	0.20	0.25	0.006	0.008	0.010
D	5.20 BSC			0.205 BSC		
D1	4.35 BSC			0.171 BSC		
E	5.55 BSC			0.219 BSC		
E1	6.05 BSC			0.238 BSC		
E2	3.625 BSC			0.143 BSC		
E3	1.275 BSC			0.050 BSC		
e	1.27 BSC			0.050 BSC		
L	0.45	0.55	0.65	0.018	0.022	0.026
L1	0	—	0.15	0	—	0.006
L2	0.68 REF			0.027 REF		
θ	0°	—	10°	0°	—	10°

NOTE

1. PACKAGE BODY SIZES EXCLUDE MOLD FLASH AND GATE BURRS.
MOLD FLASH AT THE NON-LEAD SIDES SHOULD BE LESS THAN 6 MILS EACH.
2. CONTROLLING DIMENSION IS MILLIMETER.
CONVERTED INCH DIMENSIONS ARE NOT NECESSARILY EXACT.